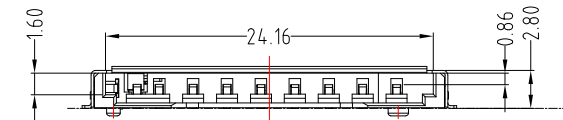


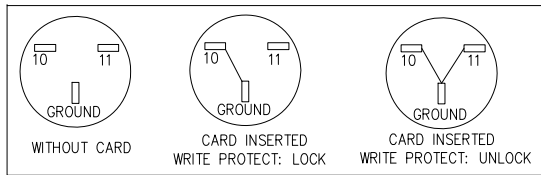
PAD AREA
 KEEP OUT AREA

RECOMMENDED P.C.B LAYOUT



SD CARD PIN DESIGN

PIN NO.	NAME	DESCRIPTION
1#	CD/DAT3	CARD DETECT/DATA I/O
2#	CMD	COMMAND
3#	VSS1	GROUND
4#	VDD	POWER
5#	CLK	CLOCK
6#	VSS2	GROUND
7#	DAT0	DATA I/O
8#	DAT1	DATA I/O
9#	DAT2	DATA I/O
10#	CD	Card Detect pin
11#	WP	Write Protect pin



- 1.MATERIAL:
- 1.1 HOUSING: LCP
 - 1.2 CONTACT: PHOSPHOR BRONZE
 - 1.3 COVER: BRASS
- 2.PLATING:
- 2.1 CONTACT: PLATED GOLD IN MATING AREA ;
TIN PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
 - 2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER

- 3.ELECTRICAL & MECHANICAL PARAMETER
- 3.1 RATING: 250V , 0.5A
 - 3.2 CONTACT RESISTANCE: 100mΩ MAX
 - 3.3 INSULATION RESISTANCE: 1000MΩ MIN
 - 3.4 WITHSTANDING STRENGTH: 500V AC
 - 3.5 INSERTION FORCE: 10N MAX
 - 3.6 SEPARATION FORCE: 2N MIN
 - 3.7 OPERATING TEMPERATURE: -25°C ~ 90°C

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :

Up to 5	±0.2
Above 5 ~ 15	±0.3
Above 15 ~ 30	±0.4
Above 30 ~ 50	±0.5
Angle	±0.3°

3RD. ANGEL'S

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	06/09/23	FINISH	MODLE	SD 短體卡座 H3.09mm
CHECKED BY:	DATE	SCALE	DWG NO.	SD-TF125001-HF-S267
Jacky Chen	06/09/23	1 : 1	PART NO.	SD-TF125001-HF-S267
APPROVED BY:	DATE	SHEET NO.	SIZE	A4
Tony Kao	06/09/23	1 of 3	VER	R1

ITEM NO.	DESCRIPTION	DRAWN	DATE
1	更新料號	Jack	060923